

4226440/A 02/2021

NOTES:

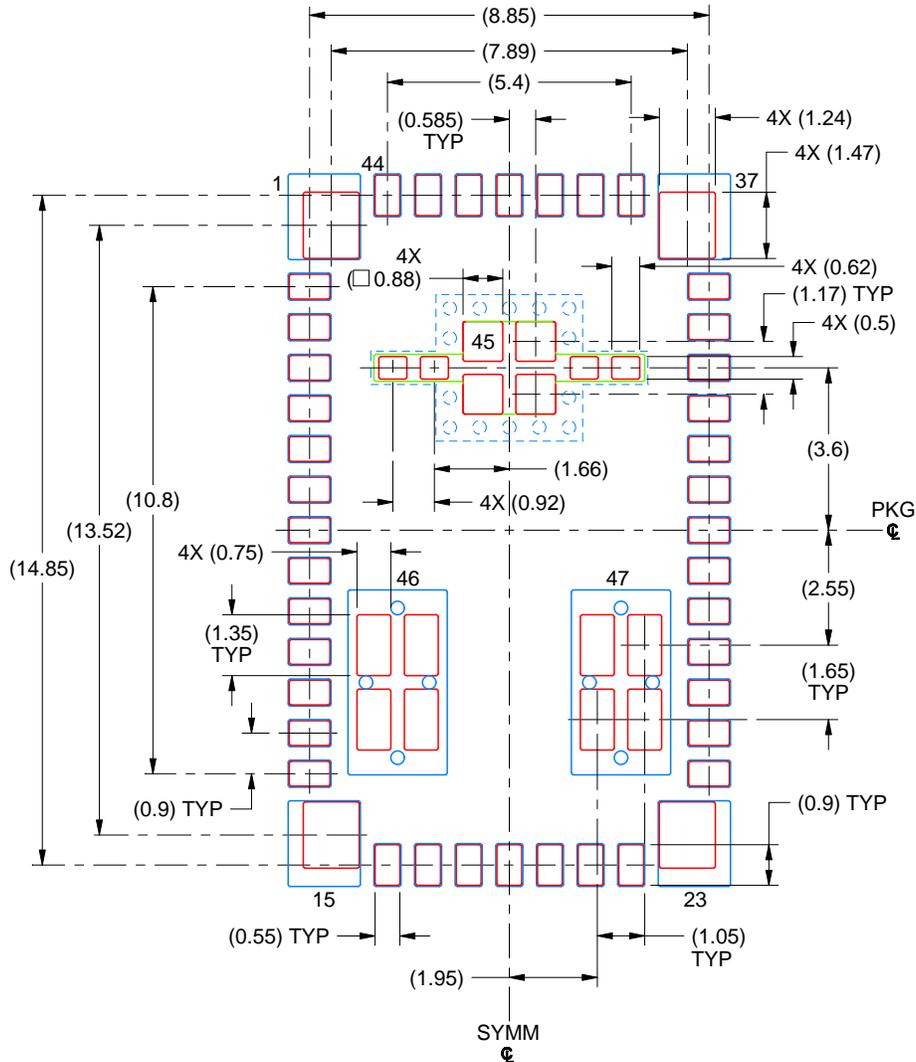
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pads must be soldered to the printed circuit board for optimal thermal and mechanical performance.

EXAMPLE STENCIL DESIGN

RUQ0047A

B1QFN - 2.95 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
 BASED ON 0.1 mm STENCIL THICKNESS

CORNER PINS 1, 15, 23 & 37:
 60% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

EXPOSED PAD 45:
 66% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

EXPOSED PAD 46 & 47:
 45% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
 SCALE:6X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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